

ABSTRACT

The invention relates to a high frequency
circuit module in which a two- or more-layer dielectric
substrate is used, the dielectric substrate between a
5 conductor line of a matching circuit on the input side
or on the output side and ground metal is composed of
two or more layers and the miniaturization is enabled
and a communication device using it.

As a required part can be thickened without
10 changing the thickness of the whole dielectric
substrate, the transmission loss can be reduced and the
miniaturization of the high frequency circuit module
and the communication device using it is enabled.